



Electronics for the Future

ROHM Corporate Profile

April 1, 2026

ROHM Co., Ltd.



Company Mission

Quality is our top priority at all times.
Our objective is to contribute to the advancement and progress of culture through a consistent supply, under all circumstances, of high quality products in large volumes to the global market.

Our Statement

Electronics for the Future

ROHM will continue to support the development of society and the enrichment of people's lives into the future by solving a variety of social issues with our electronics technology.

Management Vision

We focus on power and analog solutions and solve social problems by contributing to our customers' needs for "energy savings" and "miniaturization" of their products.

Company Overview



Company Information

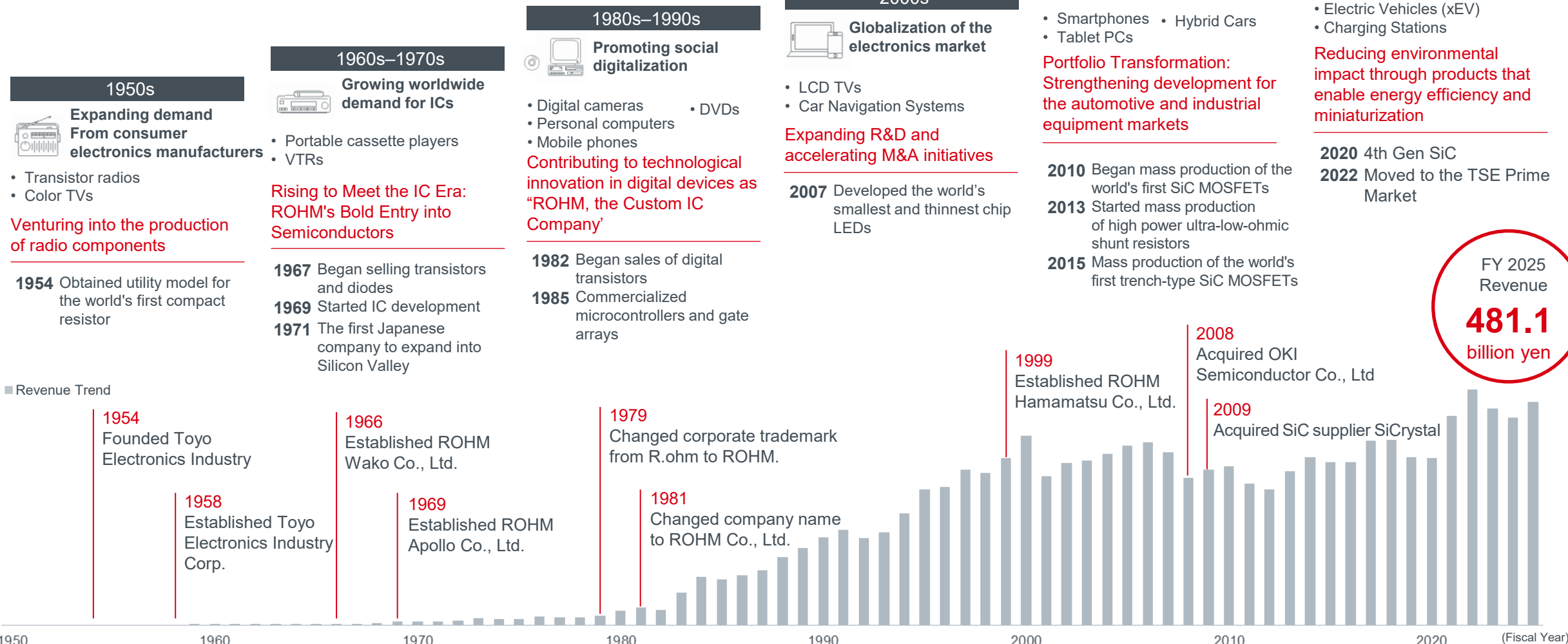
Date of Establishment	September 17, 1958
Capital	86,969 million yen (Current as of March 31, 2026)
Representative	President, Chief Executive Officer Katsumi Azuma
Net Sales	481,148 million yen (Current as of March 31, 2026)
Number of Employees	21,756 people
Group Companies	Japan: 4 Overseas: 28
Worldwide Locations	Overseas: 73 Japan: 24

Products

LSI	Analog, Logic, Memory
Semiconductor Devices	Transistors, Diodes, Power Devices, Light Emitting Diodes, Laser Diodes
Modules	Printheads, Optical Modules
Others	Resistors, etc.



A trajectory of growth built through repeated challenges and technological innovation

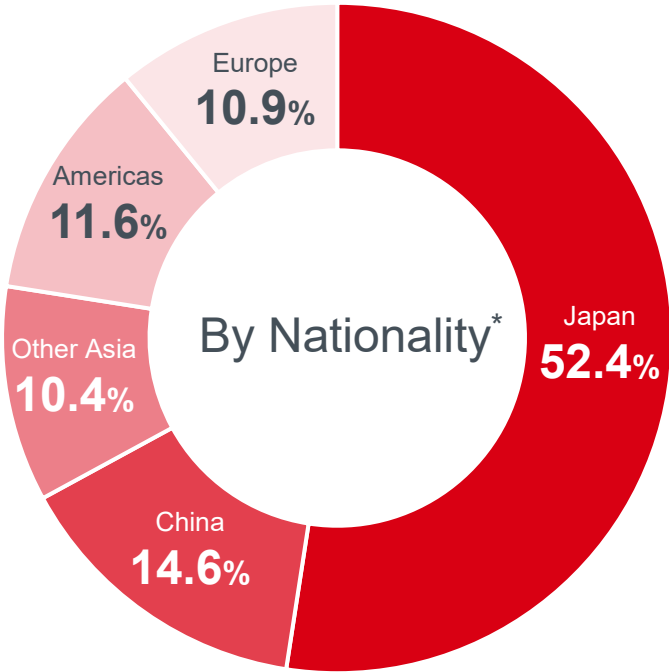
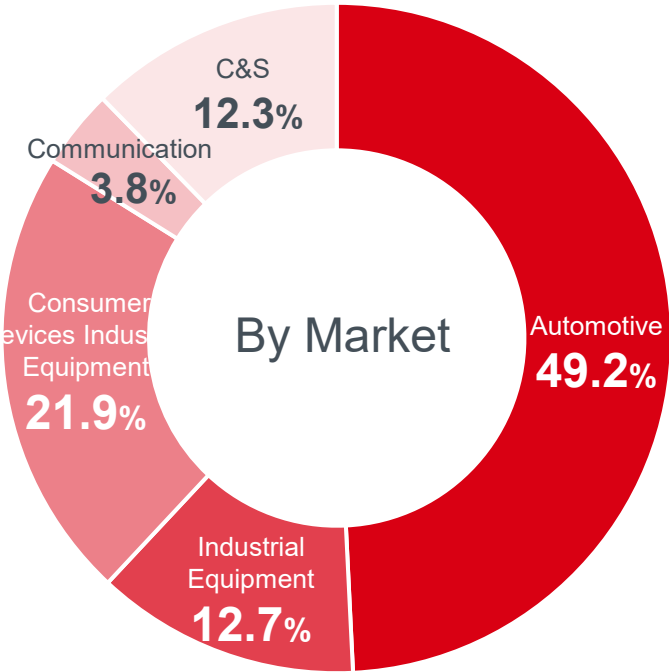
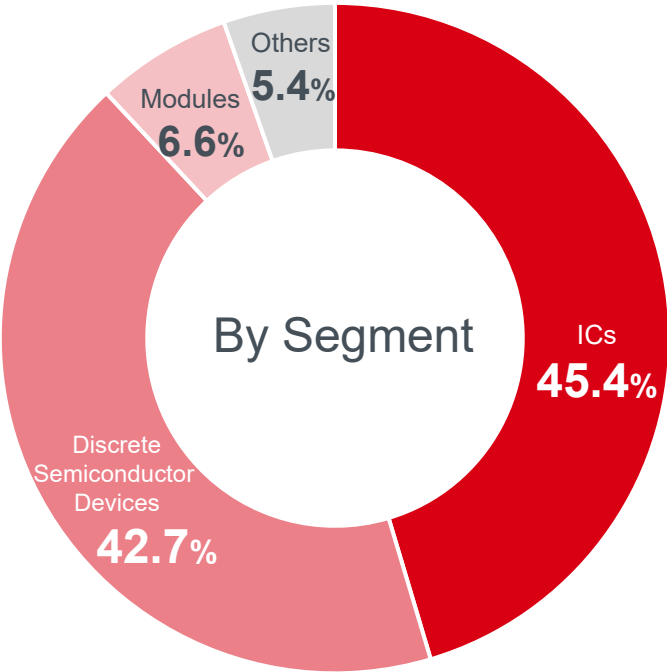


Revenue Breakdown



With a focus on semiconductors, we have a strong track record in the automotive sector, where quality requirements are especially demanding.

Revenue **481,148** million yen

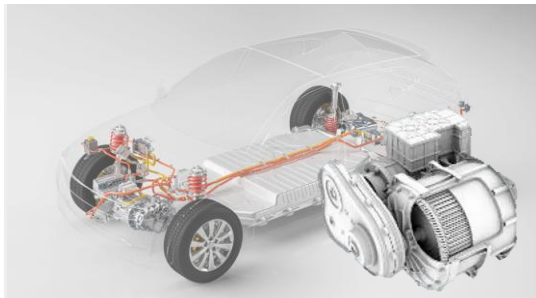


*Breakdown of business partners by Nationality
(Current as of March 31, 2026)

Target Markets and Applications

We focus on developing key products for priority markets and deliver solutions that enhance market value

Automotive Market



xEV Inverters



xEV OBC + DC-DC



ADAS / Autonomous Driving



E/E Architecture / Zone ECU

Consumer, Communications, and C&S Market



AI Servers / Data Centers



Smart Home Appliances

Industrial Equipment Market



FA / Robotics



Energy

*FA: Factory Automation, OBC: On-Board Charger, ADAS: Advanced Driver Assistance System, E/E Architecture: Electrical/Electronic Architecture, ECU: Electronic Control Unit, C&S: Computer & Storage

Comprehensive Solutions Through the Integration of Power and Analog Technologies

Power Technology



- Industry-Leading Low-Loss Performance
- Industry-Leading Reliability
- Comprehensive Lineup from Small-Signal to High-Power Devices



Analog Technology

Power Management ICs



- Industry-Leading High-Frequency Technology
- Ultra-Low Quiescent Current Technology
- Ultra-Stable Control Technology

Peripheral Devices

Driver ICs That Maximize Power IC Performance

Amplifiers, Resistors, and More



Improved System-Level Energy Efficiency

Significantly Reduced Evaluation and Development Time Through Device Optimization



Miniaturization, Space Saving, and Functional Integration

Smaller System Footprint Through Fewer External Components and High-Density Mounting

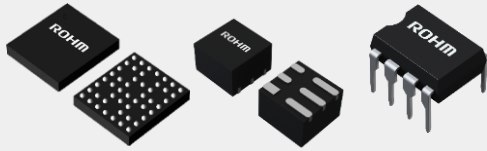


Optimized Noise and Thermal Management

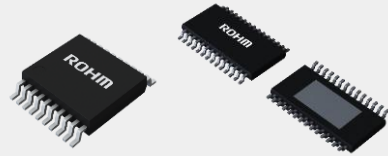
Minimized Power Loss Through the Optimal Combination of High-Efficiency Devices

Our accumulated technologies and expertise allow us to deliver comprehensive proposals to our customers

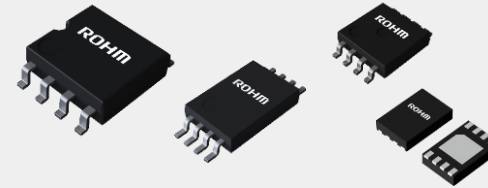
Power Management / Power Supply ICs



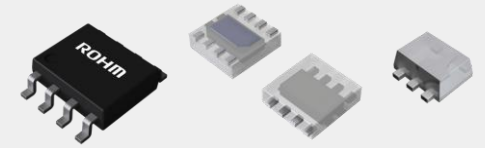
Motor/Actuator Driver ICs



General Purpose ICs



Sensor ICs



Microcontrollers

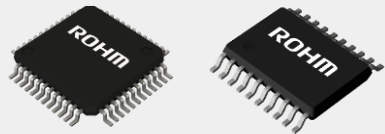
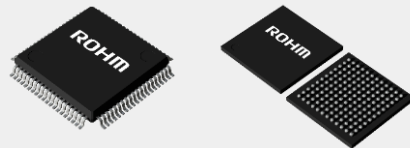


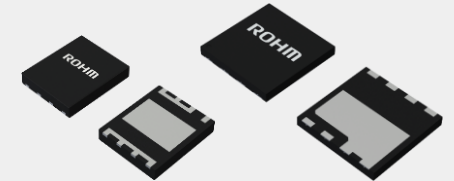
Image LSIs



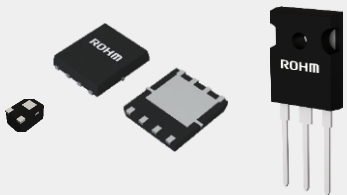
SiC Power Devices



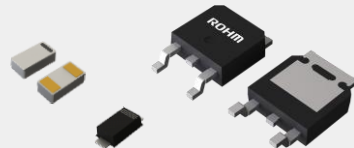
GaN Power Devices



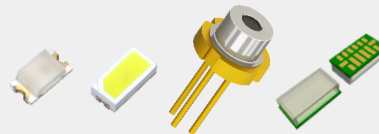
Transistors



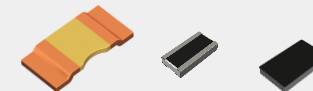
Diodes



LEDs / Laser Diodes



Resistors



Thermal Printheads



Production Sites

LAPIS Semiconductor Co., Ltd.

Relationship with Each Segment at Major Production Sites

Primarily, the front-end processes (wafer and device manufacturing) are handled at domestic facilities, while the back-end processes (assembly and inspection) are handled at overseas facilities

Front-end process (wafer and device manufacturing)

Headquarters (Kyoto)

ICs
Sensors
SiC
Transistors
LEDs
Laser Diodes

Shiga

Transistors
Diodes
IGBT

ROHM Device Manufacturing Co., Ltd.

Kasaoka (Okayama)

IC
Diodes

Hamamatsu (Shizuoka)

IC
LED
GaN

Chikugo (Fukuoka)

IC
Diodes
Transistors
SiC

LAPIS Semiconductor Co., Ltd.

Miyazaki (Miyazaki)

IC
Sensors
Diodes
SiC
IGBT

Miyagi (Ohira)

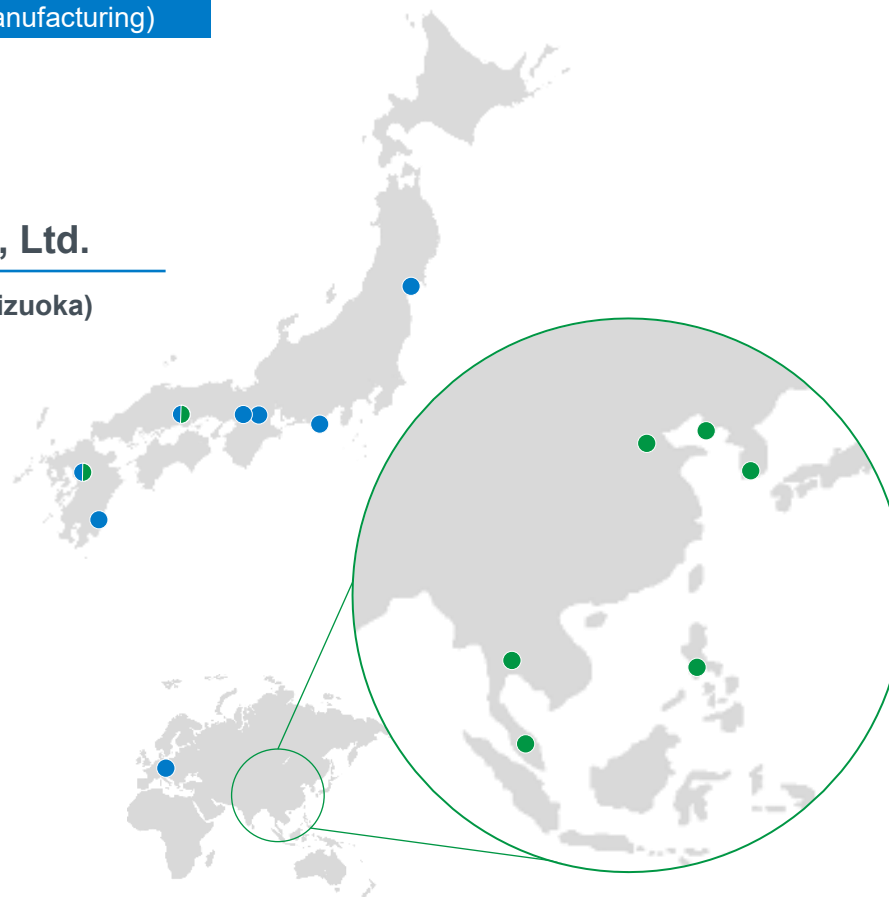
IC

Miyazaki NO.2 (Kunitomi)

SiC

SiCrystal GmbH (Germany)

*Wafer manufacturing



Back-end Process (assembly and inspection) Mother factory

ROHM Assembly Manufacturing Co., Ltd.

Kasaoka (Okayama)

Diodes
Laser Diodes
LEDs

Hirokawa (Fukuoka)

Sensors
Diodes
Transistors
Printheads

Yukuhashi (Fukuoka)

ICs

Expansion into Asia

Back-end Process (assembly and inspection)

Thailand

ICs
Transistors
Diodes
SiC
IGBT
IPM
Optical sensors
Resistors
Wireless modules

South Korea

Transistors
Diodes
SiC
IGBT

Malaysia

Transistors
Diodes
LEDs
ICs

Dalian (China)

Printheads

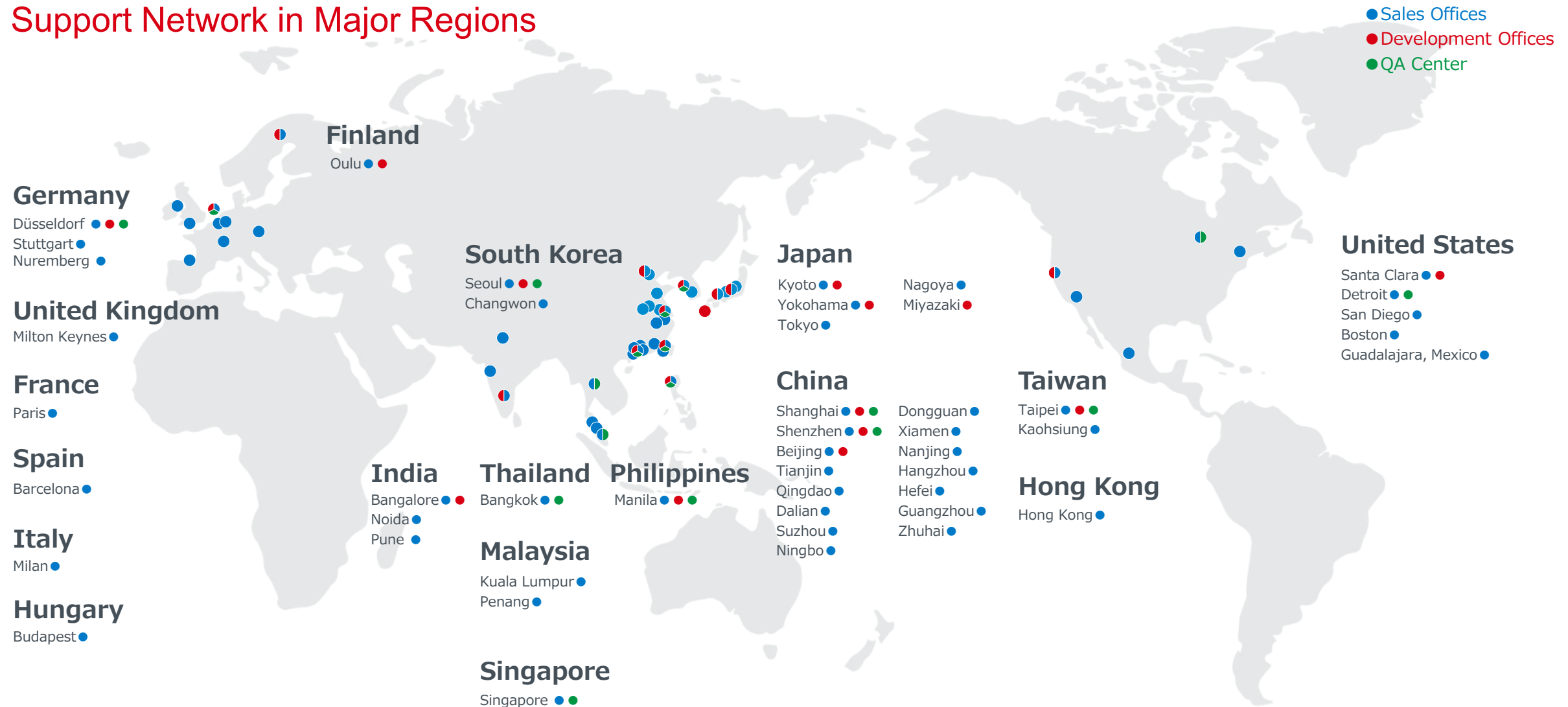
Philippines

ICs
Transistors
Diodes
Sensors
Printheads
Resistors

Tianjin (China)

Diodes
LEDs
Display
Laser Diodes
Optical sensors

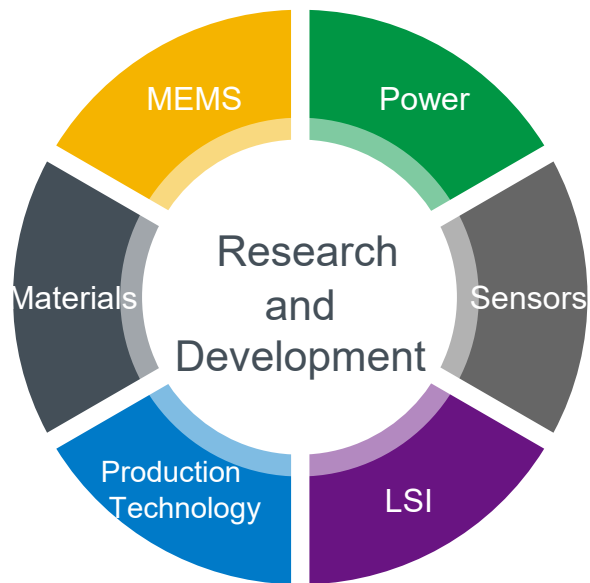
Support Network in Major Regions



Pursuing new technologies and conducting fundamental research with an eye on the future

To sustainably deliver high-quality products in large volumes worldwide, we actively embrace the challenge of the unknown and engage in fundamental research to create innovative world-first products

R&D Aligned with Societal Challenges



Electronics for the Future

Communication

Ultra-high-speed communication such as 6G

Initiatives for Social Implementation

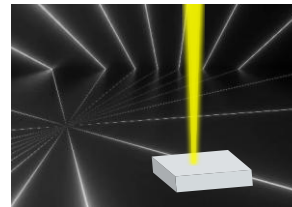


Terahertz Wave Oscillation and Detection Devices

New resonant-tunneling diodes enable ultra-small, low-power, low-cost designs
The practical application of terahertz waves enhances convenience across a wide range of fields, including sensing and communications

Sensing

Combines high-precision with low power consumption



PCSEL

Next-generation lasers achieve high directivity without a lens
Driving dramatic improvements in device performance to realize smaller, lower-cost, higher-precision LiDAR

AI and Advanced Robotics

High-efficiency energy-saving power supply systems for AI applications



NoMaDbot™

Beyond SLAM—achieving autonomous navigation without maps
Eliminates the need for mapping, reducing upfront investment and ongoing maintenance costs for autonomous navigation

*"NoMaDbot™" is a trademark or registered trademark of ROHM Co., Ltd.



Promoting 2030 Mid-term Environmental Targets through Three Key Themes

FY2030 Mid-Term Environmental Targets	Goals for 2050
Climate Change • Reduce greenhouse gas emissions by 50.5% compared to FY2018. • Promote the adoption of renewable energy (procurement ratio: 65%)	Achieve net-zero greenhouse gas emissions We consider climate change countermeasures an important indicator for measuring the effectiveness of our sustainability efforts and aim to achieve net-zero greenhouse gas emissions by 2050
Resource Recycling • Increase water recovery and reuse rate 5.5% increase compared to FY2019 • Achieve zero waste emissions	Zero Emissions Through our entire business activities, from procurement, production, to sales, we will strive to maximize resource recycling to eliminate waste of limited resources
Coexistence with Nature • We promote greening at each location Conservation of locally endemic species • Compliance with policies and regulations, Thorough management and reduction of usage	Harmonizing business activities with natural cycles We value the blessings of nature created by Earth's biodiversity, and hope to pass them on to future generations in a better state



Promoting and Developing Music Culture



1965

The Roots of Our Support for Music Culture Publication of "A Visual History of Music"



1991

Rohm Music Establishment of the Foundation

1993

Launched of the "Kyoto International Music Students Festival," Featuring Students from Five Continents



2016

Acquired the naming rights for 50 years, it opened as the "ROHM Theatre Kyoto"



Activities of the Music Foundation



Since its establishment in 1991

Over **20.5 billion yen**



Total of **5,121**

Scholarship Recipients **574**

Kyoto International Music Student Festival Participating Students **2,734**

19 countries worldwide

Education for Future Generations



Supporting Tomorrow's Engineers

Solicit applications for research, sponsor robot contests, and visit classes at schools. NHK Student Robocon / ABU Robocon (2013~), and National College of Technology Robocon (2015~)



Industry-Academia Collaboration

Established ROHM Memorial Halls (Ritsumeikan University, Doshisha University, Kyoto University, Tsinghua University (China))

Doshisha Rohm Plaza



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